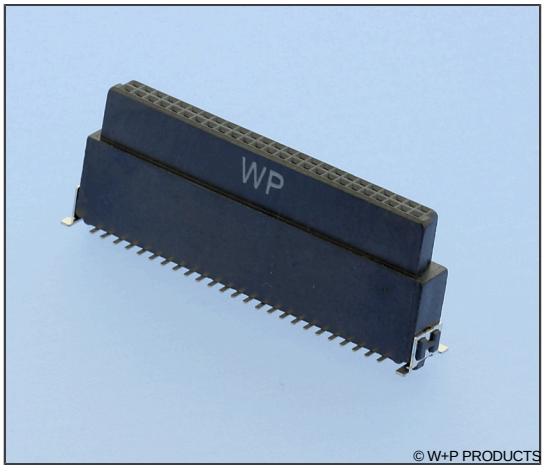
9018

SMT-Buchsenleiste RM 1,27mm, stehend

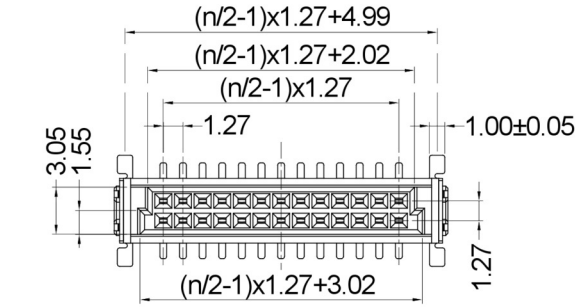
SMT Female Connector 1,27mm Pitch, vertical

Technische Daten / *Technical Data*

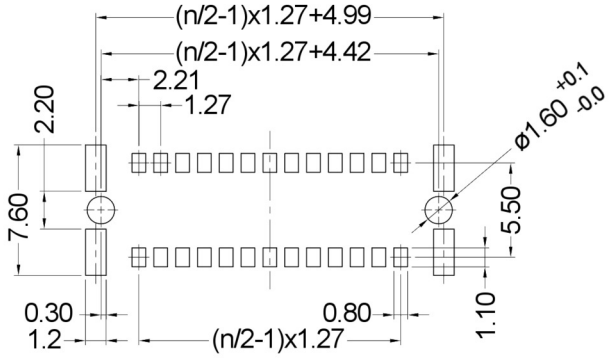
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Kupferlegierung
Contact Material	*Copper alloy*
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni
Contact Surface	*Acc. to plating options, over Ni*
Durchgangswiderstand	< 25 mΩ
Contact Resistance	*< 25 mΩ*
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	*> 1000 MΩ*
Spannungsfestigkeit	600 V AC
Test Voltage	*600 V AC*
Nennspannung	100 V AC
Voltage Rating	*100 V AC*
Nennstrom	1,7 A max.
Current Rating	*1.7 A max.*
Temperaturbereich	-55 °C ... +125 °C
Temperature Range	*-55 °C ... +125 °C*
Verarbeitung	Reflow-Lötverfahren
Processing	*Reflow soldering*

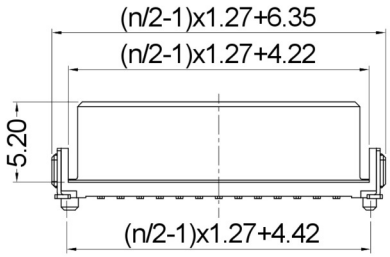


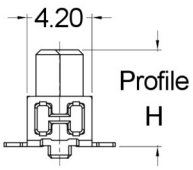
Gegenstecker / *Mating Connectors*:
9019 9020

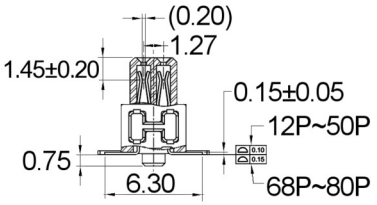


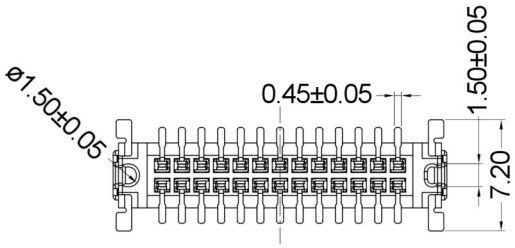
Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)

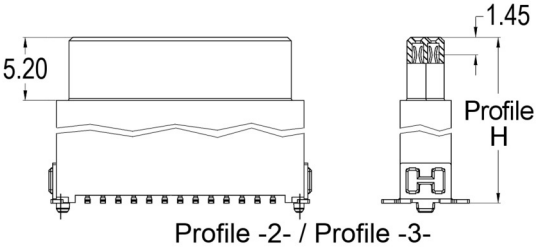












Profile -2- / Profile -3-

Series	*Contacts* *	*Profile* *	*Plating* *	*Packaging* *
9018	**50**	**1**	**80**	**TR**
	10/12/16/20/26/30 **32/40/50/68/80**	**1** H=6.25mm **2** H=9.05mm **3** H=13.65mm	**60** Sel. Au flash / Sn over Ni **80** Sel. Au 30µ" / Sn over Ni	**ST** **TR** **PPST** **PPTR**

Lieferformen / *Packaging Options:*
ST In Stangen ohne Pick&Place-Pads / *In tubes w/o Pick & Place Pads*
TR Tape & Reel ohne Pick&Place-Pads / *Tape & reel w/o Pick & Place Pads*
PPST In Stangen mit Pick&Place-Pads / *In tubes with Pick & Place Pads*
PPTR Tape & Reel mit Pick&Place-Pads / *Tape & reel with Pick & Place Pads*

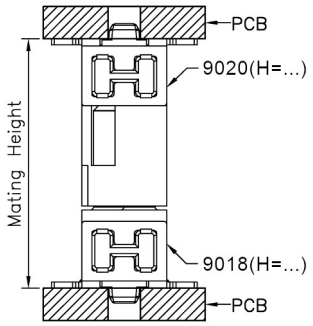
* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
please replace by your specifications.

9017 9018 9019 9020

Übersicht über die erreichbaren Bauhöhen

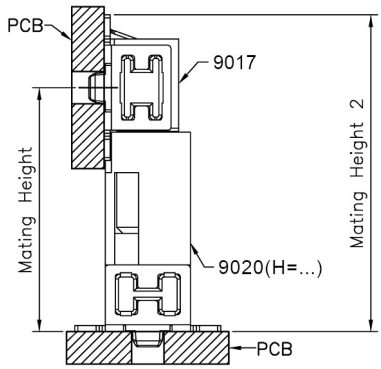
Chart of Attainable Mating Heights

9018 + 9020



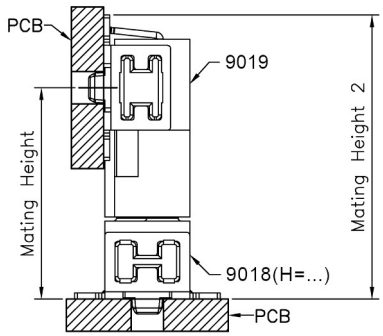
Mating Height		9020		
		H=6.75mm	H=8.25mm	H=9.85mm
9018	H=6.25mm	8.0 - 9.5	9.5 - 11.0	11. - 12.6
	H=9.05mm	10.8 - 12.3	12.3 - 13.8	13.9 - 15.4
	H=13.65mm	15.4 - 16.9	16.9 - 18.4	18.5 - 20.0

9017 + 9020



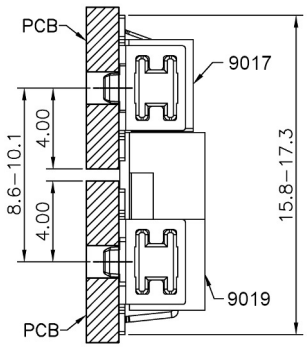
Mating Heights	9020		
	H=6.75mm	H=8.25mm	H=9.85mm
9017	8.95 - 10.45 12.55 - 14.05	10.45 - 11.95 14.05 - 15.55	12.05 - 13.55 15.65 - 17.15

9018 + 9019



Mating Heights	9018		
	H=6.25mm	H=9.05mm	H=13.65mm
9019	7.65 - 9.15 11.25 - 12.75	10.45 - 11.95 14.05 - 15.55	15.05 - 16.55 18.65 - 20.15

9017 + 9019



Für 9017 und 9019 bestehen keine Bauhöhenoptionen. Der gekennzeichnete Abstand beträgt 15.80 - 17.30mm.

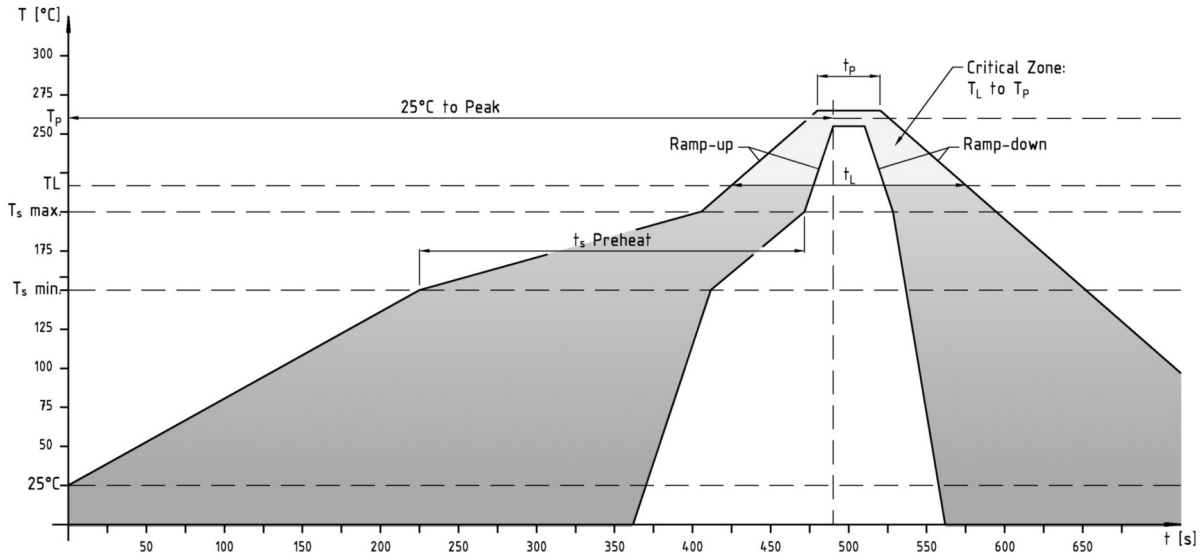
There are no profile options for 9017 and 9019. The marked dimension is15.80 - 17.30mm.

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_S$min	150 °C
Temperatur Maximum $T_S$max	200 °C
Dauer $T_S$min – $T_S$max	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_S$max – T_P	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_P$max – $T_S$min	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	**Key Values**
Minimum Temperature $T_S$min	*150 °C*
Maximum Temperatur $T_S$max	*200 °C*
Duration $T_S$min – $T_S$max	*60 – 180s*
Soldering Range Temperature T_L	*217 °C*
Duration above T_L	*60 – 180s*
Ramp-Up Rate $T_S$max – T_P	*max. 3 °C / s*
Peak Temperature T_P	*260±5 °C*
Duration Peak Temperature	*20 – 40s*
Ramp-Down Rate $T_P$max – $T_S$min	*6 °C / s*
Duration 25°C - Peak Temp. T_P	*max. 8min*